



SOT684-4

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	14-9-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	0.8	-	0.85	0.9	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	56	-	

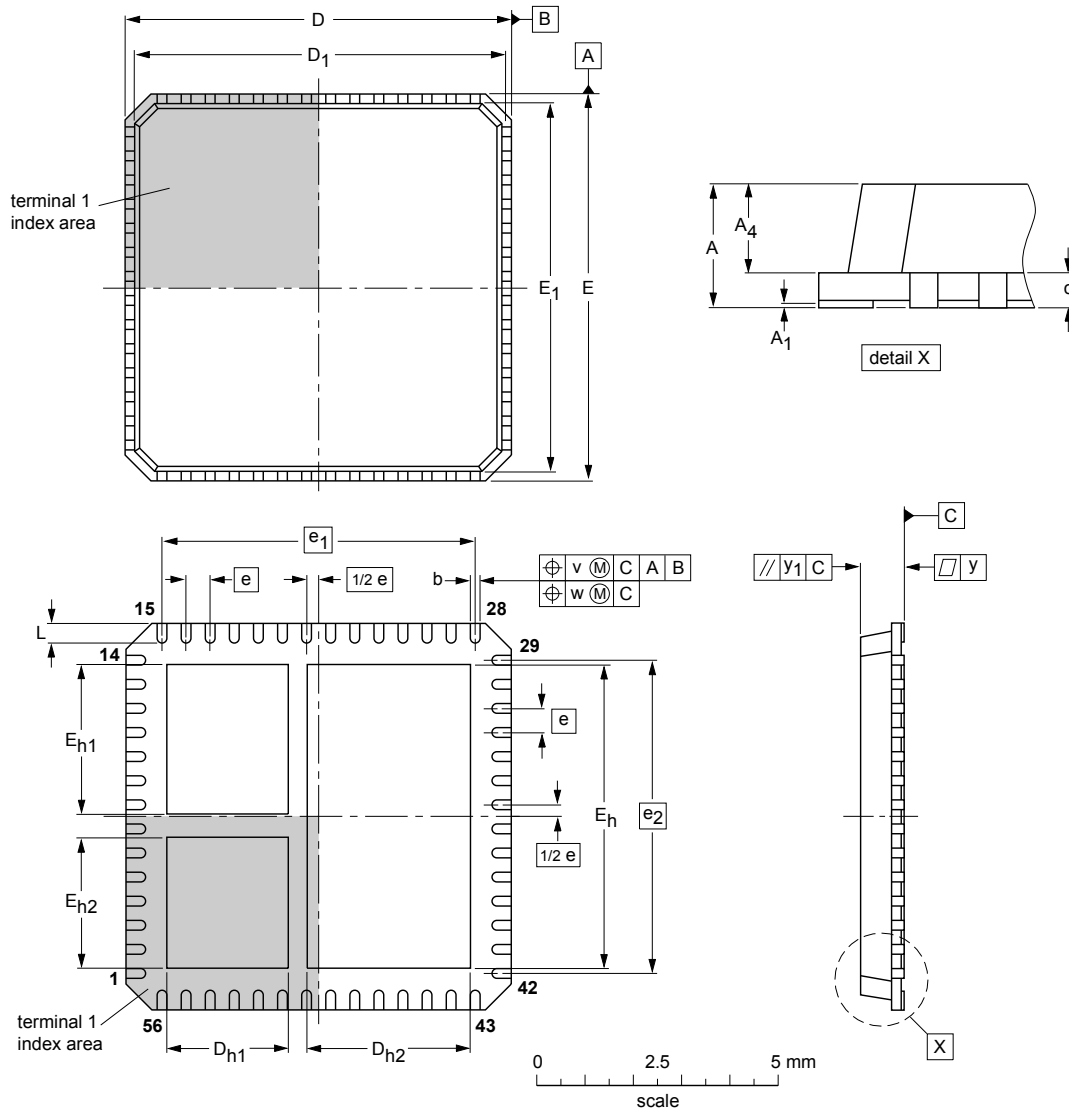


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2. Package outline

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₄	b	c	D	D ₁	D _{h1}	D _{h2}	E	E ₁	E _h	E _{h1}	E _{h2}	e	e ₁	e ₂	L	v	w	y	y ₁
mm	0.9	0.05 0.00	0.70 0.65	0.30 0.18	0.2	8.1 7.9	7.8 7.7	2.65 2.35	3.55 3.25	8.1 7.9	7.8 7.7	6.45 6.15	3.25 2.95	2.85 2.55	0.5	6.5	6.5	0.5 0.3	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT684-4	---	MO-220	---			03-10-23 04-09-14

Fig. 1. Package outline HVQFN56 (SOT684-4)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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